

Next-Generation Wafer Appearance Inspector OVS-5120 Series



[Five major features]

1) Surprising detectability

- Never puts conforming articles in defective products.

2) Exceptional reproducibility

- Stably detects defective products thanks to special lighting and software.

3) Excellent onsite response

- Employs software to absorb differences among lots.

4) Easy to use

- Equipped with Okano's unique, epoch-making learning software.

5) Surviving the intensifying competition

- Low-cost, high-performance machine.



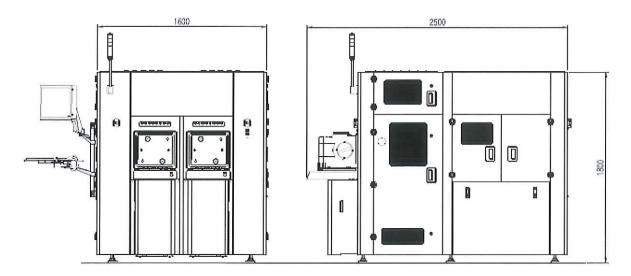
The machine sets wafers supplied from the load port on the YX0 stage and detects critical defects by using a high-speed, high-resolution color area camera.

A new model with a ling camera will be added in the spring of 2016.

[Product specifications]

Nº	Item	OVS-5120 Series
(1)	Target products	System LSIs, flash memories, CMOS devices, etc.
(2)	Wafer size	12 inches
(3)	Types of defects	Pattern defects, scratches, color irregularities, foreign matters, etc.
(4)	Camera	4 million pixels, color
(5)	Lighting	Coaxial vertical illumination and oblique light ring illumination
(6)	Inspection	2.5x, 5x and 10x (with active autofocus)
	magnification	
(7)	Resolution	1.1 µm/pixel (5x)
(8)	Processability	Approx. 2.5 minutes/(12 inches) with 2.2-µm resolution
		*Differs depending on conditions.
(9)	Option	Inker, communications specifications (Details separately discussed)
(10)	Machine dimensions	1,600 (W) x 2,500 (D) x 1,800 (H) mm
(11)	Machine weight	Approx. 2,000 kg
(12)	Control mode	PC control
(13)	Utility power supply	200 VAC, 3 phases, 30 Amps. Air: 0.5MPa

External view



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